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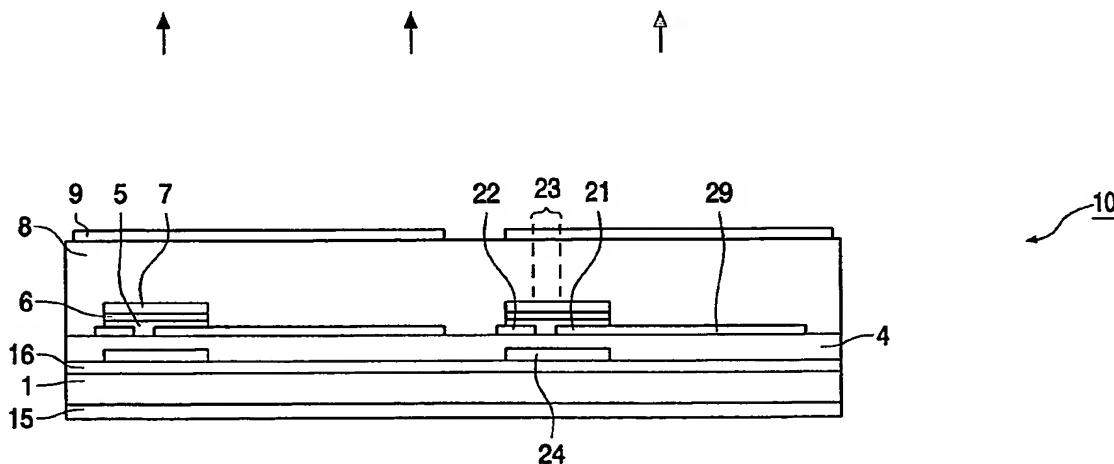
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[Continued on next page]

(54) Title: **METHOD OF MANUFACTURING A FLEXIBLE ELECTRONIC DEVICE AND FLEXIBLE DEVICE**



(57) Abstract: An electrical element, such as a thin-film transistor, is defined on a flexible substrate, in that the substrate is attached to a carrier by an adhesive layer, and is delaminated after definition of the transistor. This is for instance due to illumination by UV-radiation. An opaque coating is provided to protect any semiconductor material. A heat treatment is preferably given before application of the layers of the transistor to reduce stress in the adhesive layer.



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